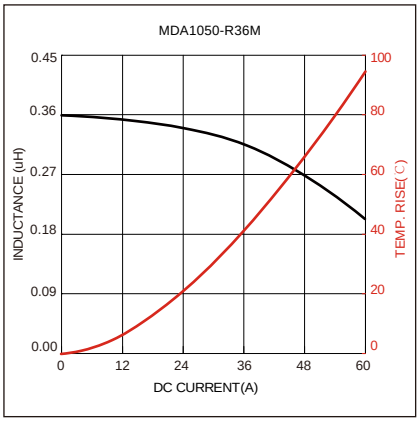
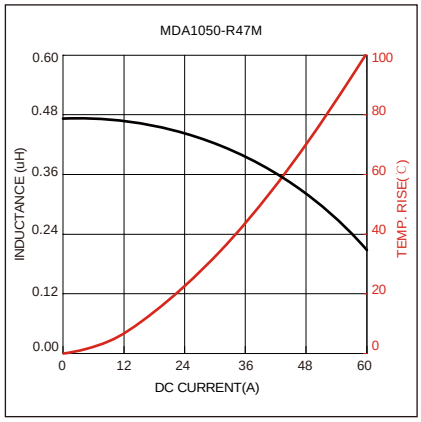
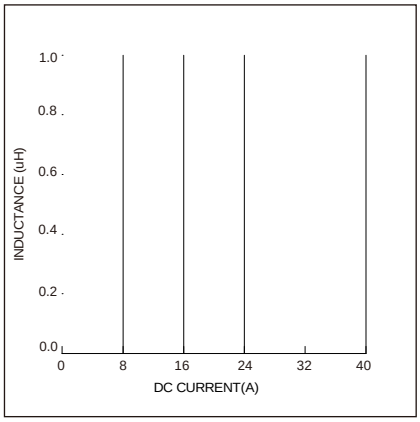
**MDA Series**
SMD Low Profile High Current Molded Inductor
Size 1050

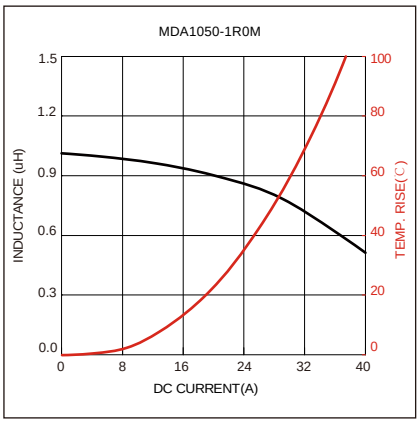
| Part No | Inductance @ 100KHz/1V | Tolerance | Temperature Rise Current Typ. (A) | Current Typ. (A) | DC Resistance Typ. | DC Resistance Max. | E |
|---|---|---|---|---|---|---|---|
| | | | | | | | |
| | | | | | | | |

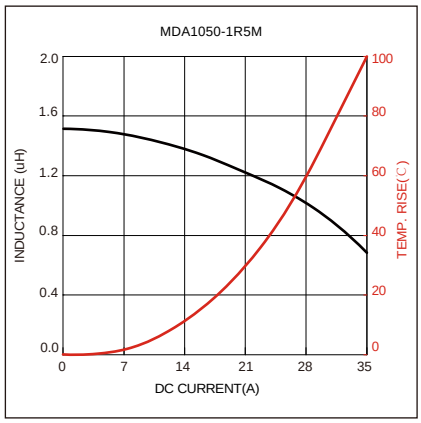
## Typical Electrical Characteristics:

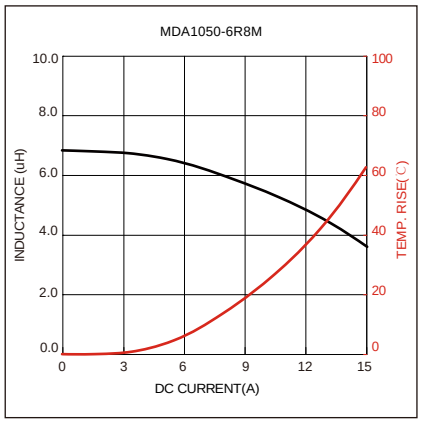


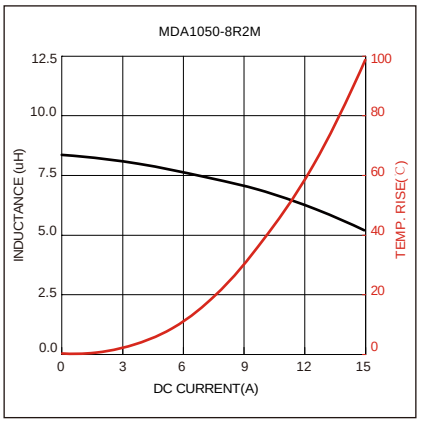



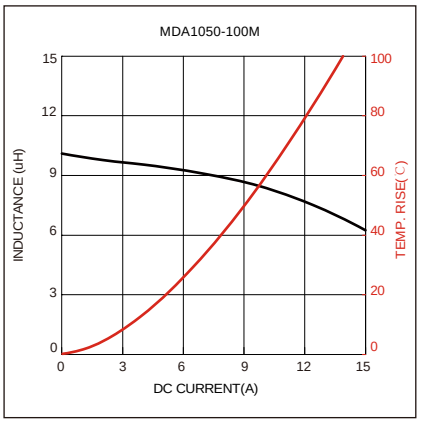



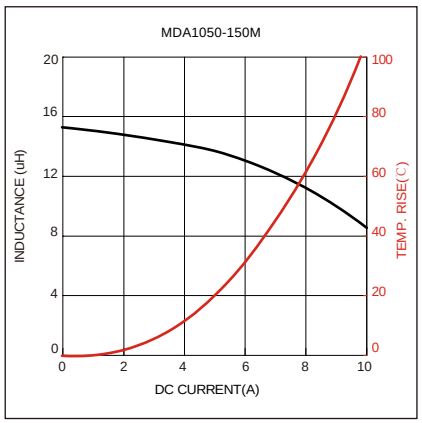



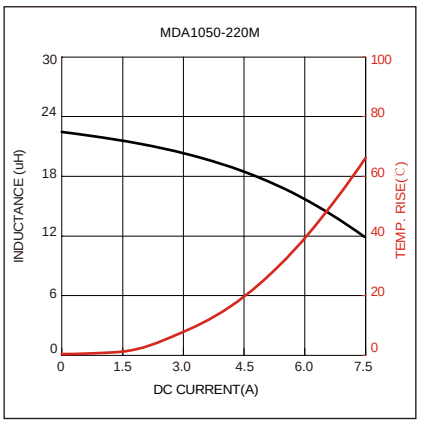



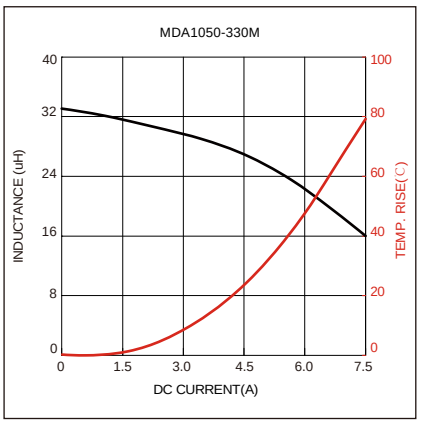

MDA1050-6R8M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
10.0
8.0
6.0
4.0
2.0
0.0
100
80
60
40
20
0
0
3
6
9
12
15

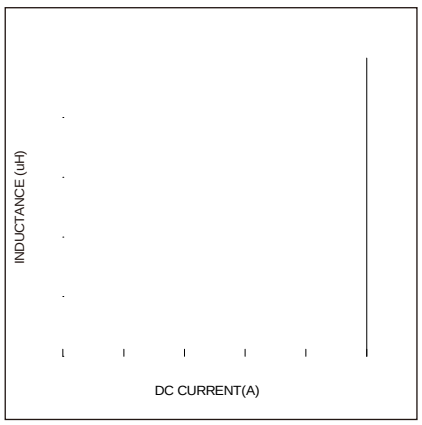

MDA1050-8R2M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
12.5
10.0
7.5
5.0
2.5
0.0
100
80
60
40
20
0
0
3
6
9
12
15


MDA1050-100M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
15
12
9
6
3
0
100
80
60
40
20
0
0
3
6
9
12
15

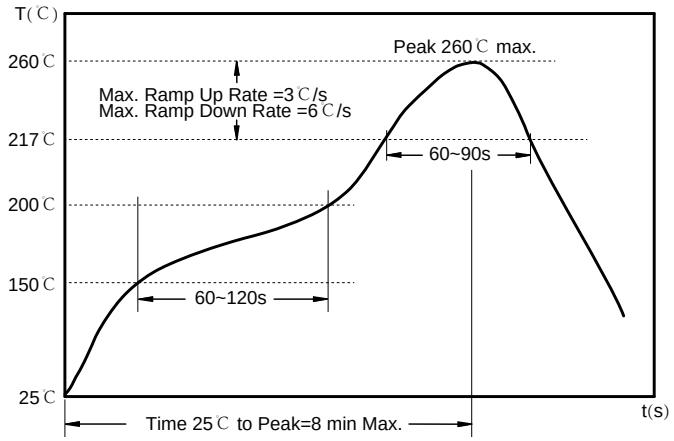

MDA1050-150M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
20
16
12
8
4
0
100
80
60
40
20
0
0
2
4
6
8
10


MDA1050-220M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
30
24
18
12
6
0
100
80
60
40
20
0
0
1.5
3.0
4.5
6.0
7.5


MDA1050-330M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
40
32
24
16
8
0
100
80
60
40
20
0
0
1.5
3.0
4.5
6.0
7.5


INDUCTANCE (uH)
DC CURRENT(A)

## Soldering Reflow:




Preheat condition: 150 ~200℃/ 60~120 sec.

Allowed time above 217℃: 60~90 sec.

Max temperature: 260℃.

Max time at max temperature: 10 sec.

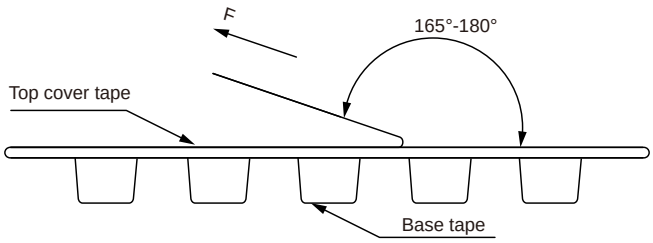
Allowed Reflow time: 2x max.

## Packaging Information:

Tape Dimension:

| Series | A0 (mm) | B0 (mm) |
|---|---|---|
| MDA1050 | 10.4 ± 0.1 | |

Peel force of top cover tape:

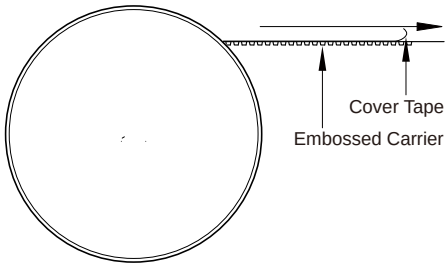



The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

| | |
|---|---|
| Marking | KH+Printing Inductance+period) |

Reel Dimension：[mm]




Packaging Quantity: